

TOSOH SMD

Sputter Sentry™

Process Monitor for Sputtering Targets

- Early warning for target erosion
- Detects sputter at the end of target life
- Closed loop compensation
- Real-time and historical data collection
- Remote data acquisition with wireless



Copper Anodes

From 4N to 6N Purity

- High conductivity
- Excellent performance for sputter target applications
- Available in bulk or plate form



Extensive sputter Precursor for W-CVD

Ru



THE GLOBAL LEADER in TARGET



ISO 14001

Collo-Spray™

Double the target life with superior uniformity

Al



Ti

Advanced PVD Materials for 300mm Wafers

Cu



Co

Ta



Characterize Your CMP and Post-CMP Processes with Dimension Vx AFP



THE GLOBAL LEADER

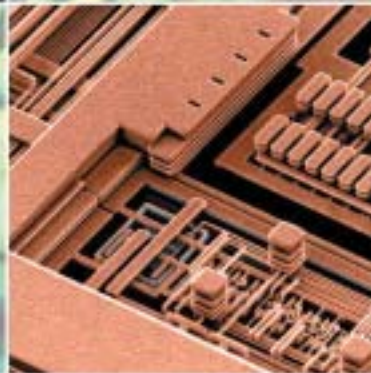
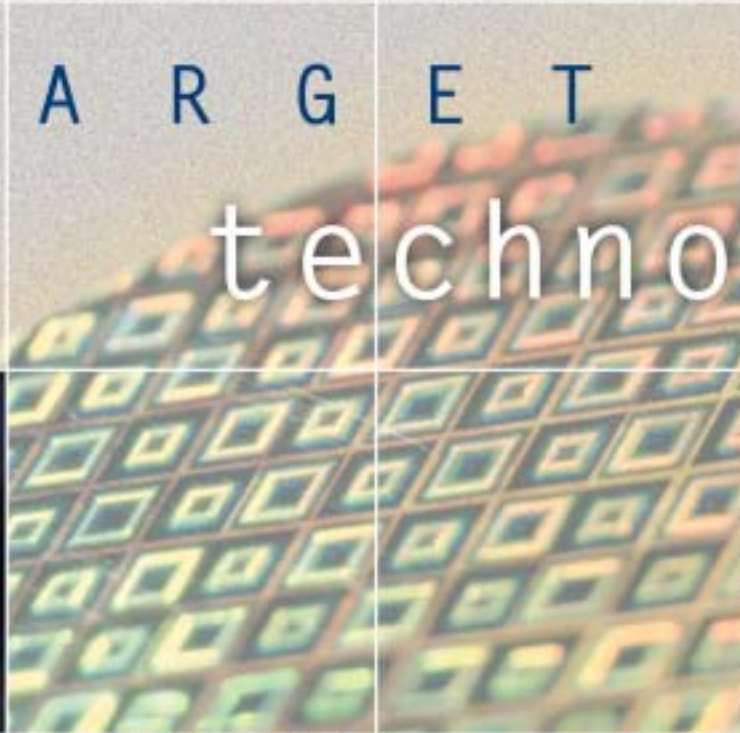
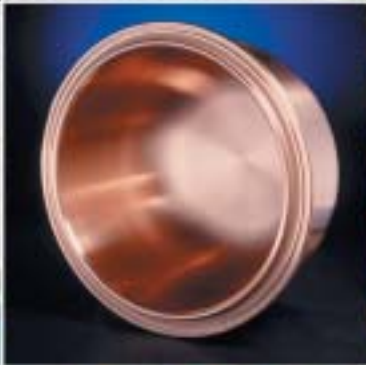
in

QS 9000

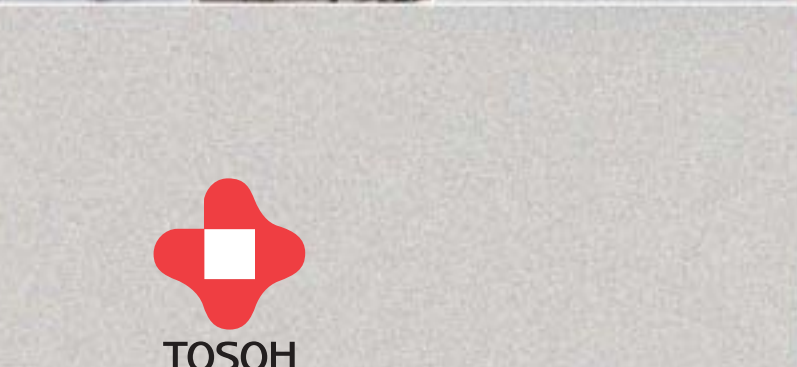


T A R G E T

technology™



ISO 9001



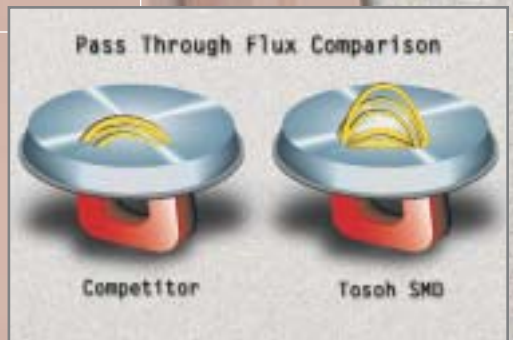
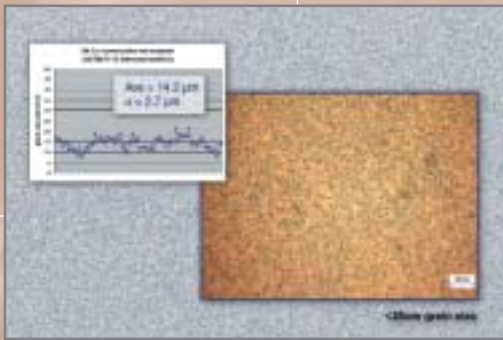
ISO 14001



Advanced PVD Materials

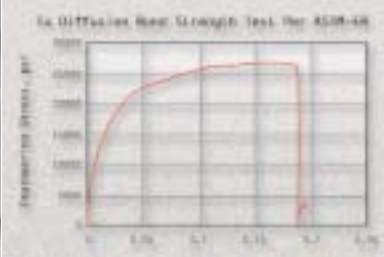
for 300mm Wafers

Cu



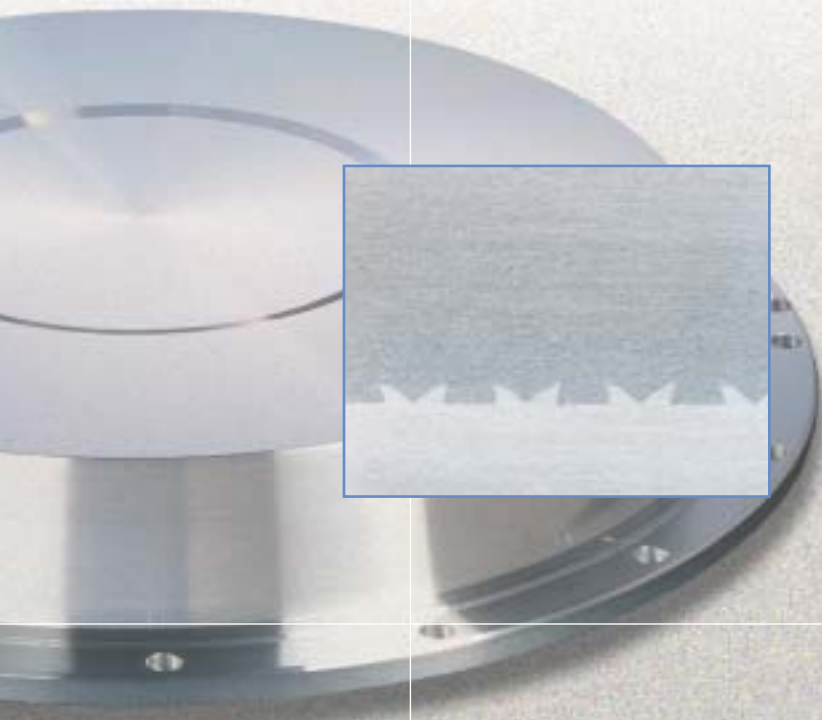
Co

Ta



Solo Xtreme™

Double the Target Life
with Superior Uniformity



Ti



Ti

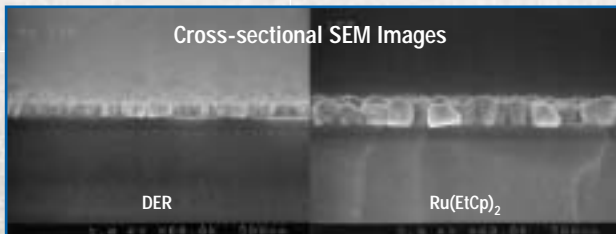


TOSOH

Ruthenium DER

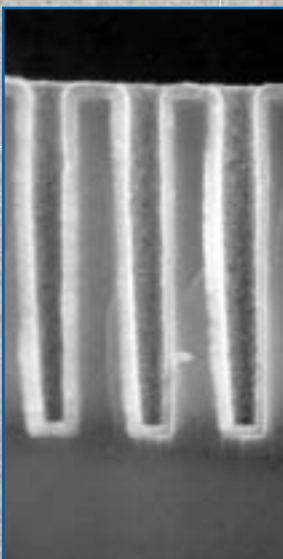
Precursor for

MO - CVD



- High vapor pressure and excellent thermal stability
- Eliminates need for Ru seed layer when deposited on SiO₂ substrate
- Smoother surface morphology and highly oriented Ru films
- Higher nucleation density than Ru(EtCp)₂

Ru



Sputter Sentry™

Process Monitor for Sputtering Targets

- Early warning for target arcing
- Sends alarm at the end of target life
- Clean room compatible
- Real-time and historical data evaluation
- Remote data acquisition and analysis



Copper Anodes

from
4N to 6N Purity

- High conductivity
- Better resistance to electromigration
- Available in pure or phosphorized form
- Consistent, fine grain microstructure

